
臺灣大學應用力學研究所
演 講 公 告

主 講 人：沈立軒部門經理

科盛科技股份有限公司研發一處

講 題：IC 封裝模擬分析及應用

主 持 人：陳國慶所長

時 間： 111年10月24日（星期一）下午2時20分開始

地 點： 臺灣大學應用力學研究所國際會議廳

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IC封裝模擬分析及應用

IC Packaging Simulation Analysis and Application

沈立軒部門經理

科盛科技股份有限公司研發一處

Plastic chip packaging is a technology that uses epoxy molding compound (EMC) to provide chip protection against physical damage. Due to the complexity and demanding geometric conditions of multi-material components, the advanced IC packaging process requires accurate numerical simulations to predict processing difficulties.

In this talk, I will share and discuss the following topics:

- How can numerical simulations help with IC packaging?
- What are the possible defects in the filling process, such as bubbles and voids and the effect of filler distribution?
- What problems may arise during temperature changes and phase transitions?

There are still many problems we need to face. In the future, we can work together from many aspects to help the IC packaging industry continue to progress.